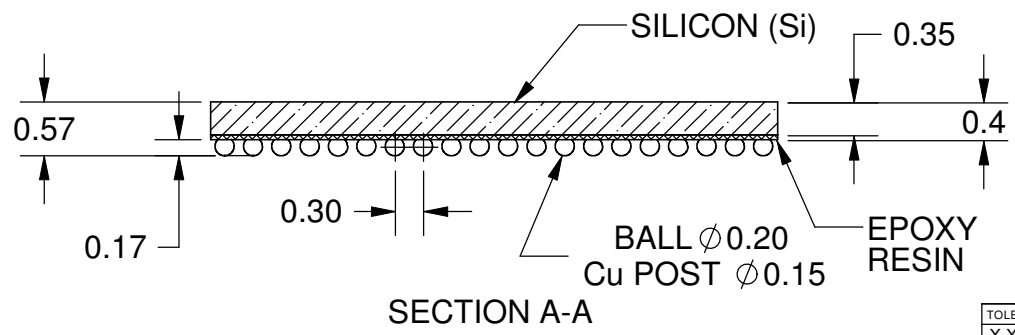
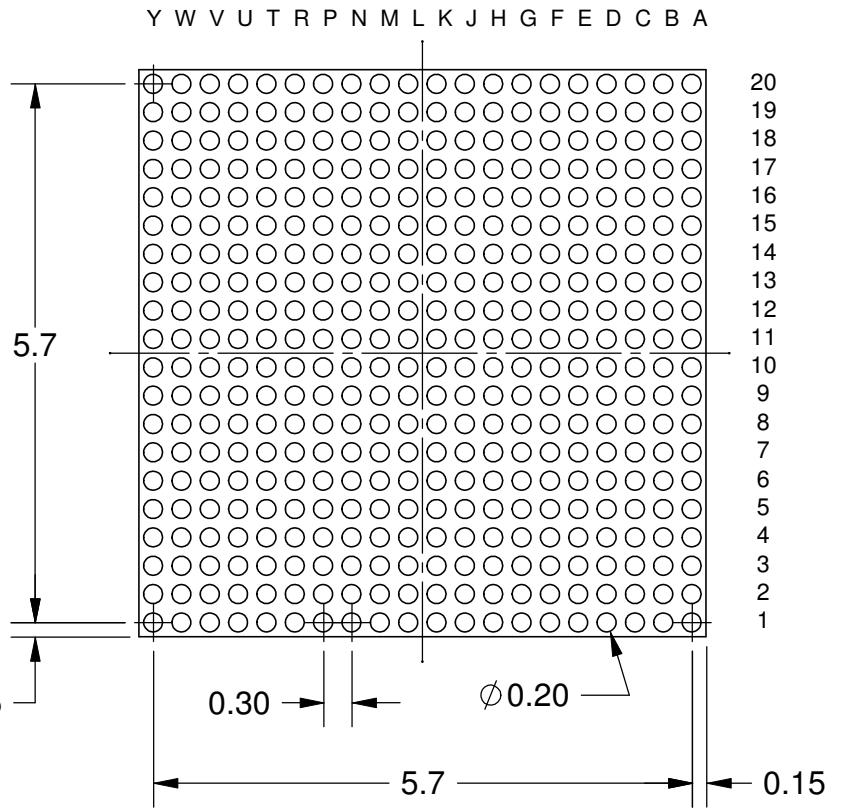
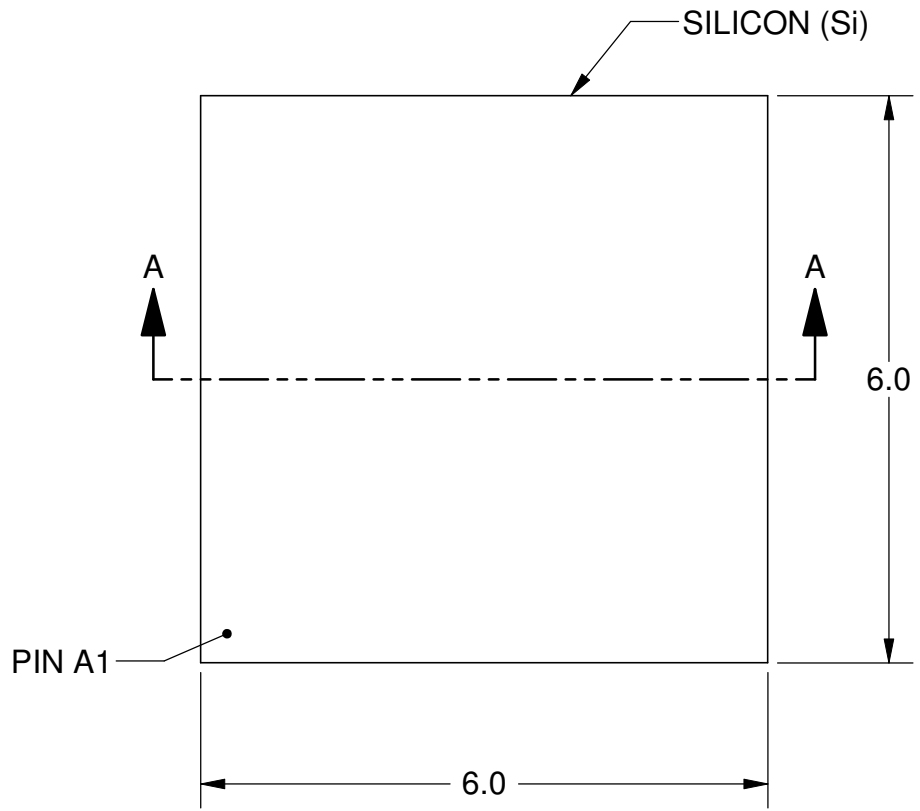


TOP VIEW

BALL VIEW



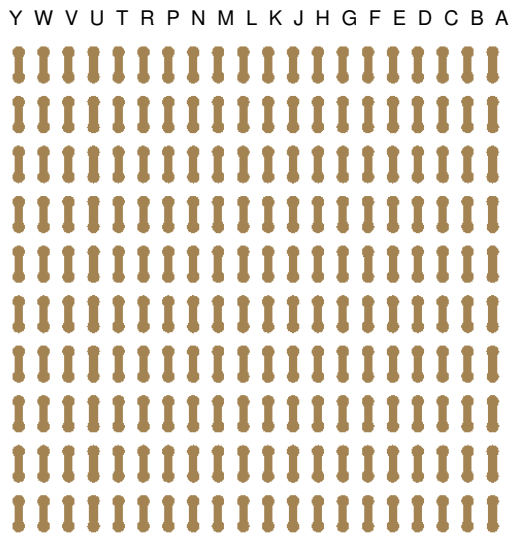
- Notes: (Unless Otherwise Specified).
 1) ALL DIMENSIONS ARE IN MM.
 2) SOLDER BALL ALLOY:
 STANDARD: SAC305 (Sn96.5/Ag3.0/Cu0.5).
 SPECIAL: LF35 (Sn98.3/Ag1.2/Cu0.5).
 3) BALL DIAMETER (BEFORE REFLOW): 0.20mm.
 4) NON-SOLDER MASK DEFINED PAD.
 5) PAD Cu DIAMETER: 0.15mm.
 6) SUBSTRATE MATERIAL: Si (SILICON).
 7) DAISY CHAIN PATTERN (SEE PAGE 2).

SECTION A-A

PART NUMBER TABLE				
PART NUMBER	BALL ALLOY	Pb-FREE	RoHS	Si DIE
WLP400T.3C-DC208D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES
WLP400T.3C1-DC208D	Sn98.3/Ag1.2/Cu0.5	YES	YES	YES

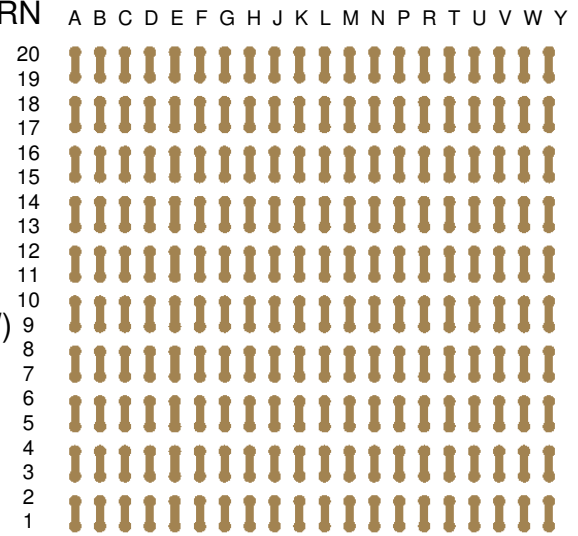
TOLERANCE UNLESS NOTED		APPROVALS		DATE	TopLine [®]	TITLE WLP400T.3C-DC208D 400-BALL P=0.3mm (TEG0306)				
X.X	+/- 0.3	DRAWN J. Hines		12/28/2010						
X.XX	+/- 0.03	ENG								
X.XXX	+/- 0.003	MFG			SCALE	SIZE	DRAWING NO.		REV	
ANGLES +/- 0.5°		THIRD ANGLE PROJECTION			12.5:1	A	532082		A	
ALL DIMENSIONS IN		<input type="checkbox"/> INCHES <input checked="" type="checkbox"/> MILLIMETERS		REVISED	DO NOT SCALE DRAWING				SHEET 1 OF 2	

BALL VIEW

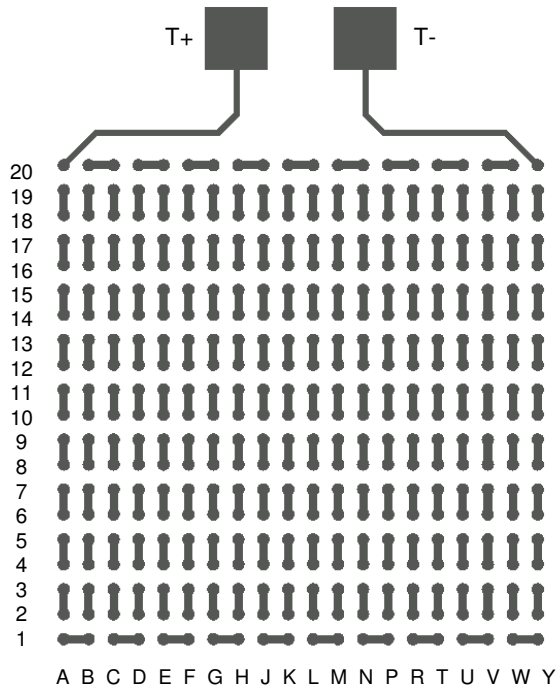


DAISY CHAIN PATTERN

BOTTOM SIDE
(TOP X-RAY VIEW)

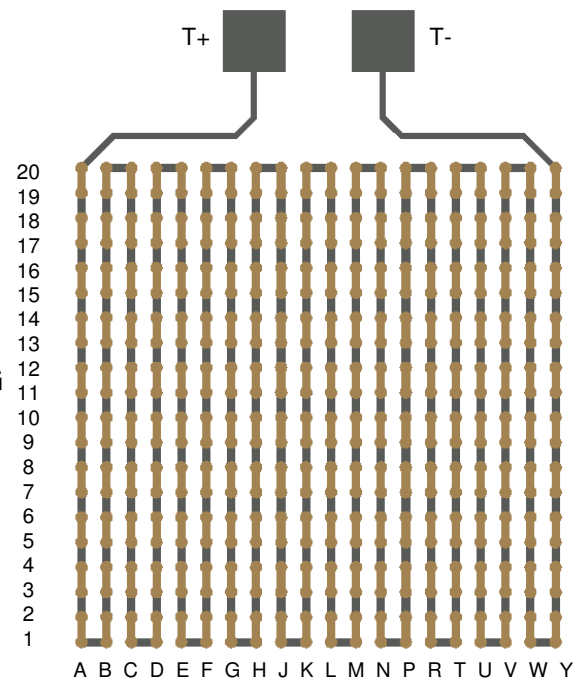


TOP VIEW



TEST VEHICLE BOARD

AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.15mm (5.9mil).
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.10mm (3.9mil).

TopLine ®			
TITLE WLP400T.3C-DC208D 400-BALL P=0.3mm (TEG0306)			
SCALE 11:1	SIZE A	DRAWING NO. 532082	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 2	